

Features

- High speed 10MBit/s
- High isolation voltage between input and output (Viso=5000 Vrms)
- Guaranteed performance from -40°C to 85°C
- Wide operating temperature range of -55°C to 100°C
- Regulatory Approvals
 - UL UL1577 (E364000)
 - VDE EN60747-5-5(VDE0884-5)
 - CQC GB4943.1, GB8898
 - IEC60065, IEC60950

Description

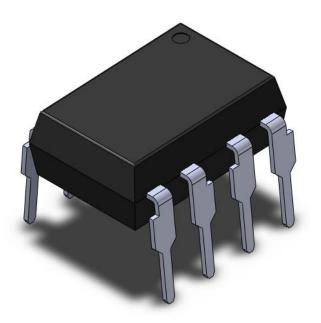
The 6N137, CT2601 optocouplers consist of a 850 nm AlGaAS LED, optically coupled to a very high speed integrated photo-detector logic gate with a strobable output. This output features an open collector,

there by permitting wired OR outputs. The switching parameters are guaranteed over the temperature range of -40°C to +85°C. A maximum input signal of 5mA will provide a minimum output sink current of 13mA (fan out of 8).

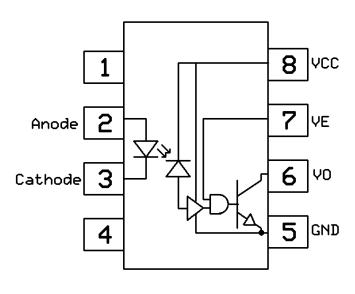
Applications

- Line receivers
- Telecommunication equipment
- Feedback loop in switch-mode power supplies
- Home appliances

Package Outline



Schematic



Note: Different lead forming options available. See package dimension.





Absolute Maximum Rating at 25°C

Symbol	Parameters	Ratings	Units	Notes
Viso	Isolation voltage	5000	V _{RMS}	1
Topr	Operating temperature	-55 ~ +100	°C	
Тѕтс	Storage temperature	-55 ~ +125	°C	
TsoL	Soldering temperature	260	°C	2
Emitter				•
lF	Forward current	50	mA	
VR	Reverse voltage	5	V	
Pı	Power dissipation	100	mW	
Detector				
Po	Power dissipation	85	mW	
lo	Average Output current	50	mA	
Vo	Output voltage	7.0	V	1min(Max.)
Vcc	Supply voltage	7.0	V	
VE	Enable Input Voltage Not to Exceed VCC by more than 500mV	5.5	V	

Notes

- 1. AC for 1 minute, $RH = 40 \sim 60\%$.
- 2. For 10 second peak



Electrical Characteristics

 $T_A = -40 - 85$ °C (unless otherwise specified). Typical values are measured at $T_A = 25$ °C and $V_{CC} = 5V$

Emitter Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
VF	Forward voltage	IF = 10mA	-	1.4	1.6	V	
VR	Reverse Voltage	IR = 10μA	5.0	-	-	V	
ΔV _F /ΔT _A	Temperature coefficient of forward voltage	IF =10mA	-	-1.8	-	mV/°C	

Detector Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
1	Logic High Supply Current	I _F =0mA, V _E =0.5V, V _{CC} =3.3V	-	4.0	10	m 1	
Іссн	Logic High Supply Current	I _F =0mA, V _E =0.5V, V _{CC} =5.5V	-	6.5	10	mA	
l	Logic Low Cupply Current	I _F =10mA, V _E =0.5V, V _{CC} =3.3V	-	5.5	13	m 1	
ICCL	Logic Low Supply Current	I _F =10mA, V _E =0.5V, V _{CC} =5.5V	-	8.8	13	mA	
\/	High Lavel Enable Voltage	I _F =10mA, V _{CC} =3.3V	2.0	-	-	V	
V _{EH}	High Level Enable Voltage	I _F =10mA, V _{CC} =5.5V	2.0	-	-	V	
V	Low Lovel Engble Voltage	I _F =10mA, V _{CC} =3.3V	-	-	0.8	V	
VEL	Low Level Enable Voltage	I _F =10mA, V _{CC} =5.5V	-	-	0.8	V	
	High Loyal Enable Current	V _E =2.0V, V _{CC} =3.3V	-	-0.2	-1.6	mA	
I _{EH}	High Level Enable Current	V _E =2.0V, V _{CC} =5.5V	-	-0.53	-1.6	IIIA	
1	Low Level Enable Current	V _E =0.5V, V _{CC} =3.3V	-	-0.42	-1.6	mA	
lel	Low Level Enable Current	V _E =0.5V, V _{CC} =5.5V	-	-0.75	-1.6	IIIA	

Transfer Characteristics

Symbol	Parameters	Test Conditions	Min	Тур	Max	Units	Notes
		Vcc=3.3V, Vo=0.6V,		1.6	5	4	
	Jamest Thread and Correct	V _E =2.0V, I _O =13mA	-	0.1	5		
IFT	Input Threshold Current	Vcc=5.5V, Vo=0.6V,		2.5	-	mA	
		V _E =2.0V, I _O =13mA	-	2.5	5		





		I _F =250μA, V _O =V _{CC} =3.3V,		7.0	100		
Іон	Logic High Output Current	V _E =2.0V	•	7.0	100	μΑ	
IOH	Logic riigii Odipai Carreni	I _F =250μA, V _O =V _{CC} =5.5V,		2.0	100	μΑ	
		V _E =2.0V		2.0	100		
		I _F =5mA, V _{CC} =3.3V, V _E =2.0V,		0.45	0.6		
Vol	Low Level Output Voltage	Io=13mA		0.43	0.6	V	
VOL	Low Level Output voltage	I _F =5mA, V _{CC} =5.5V, V _E =2.0V,		0.35	0.6	V	
		Io=13mA	-	0.35	0.6		

Electrical Characteristics

 $T_A = -40 - 85$ °C (unless otherwise specified). Typical values are measured at $T_A = 25$ °C, $V_{CC} = 5V$ and $I_F = 7.5$ mA

Switching Characteristics

Symbol	Parameters	Test Co	nditions	Min	Тур	Max	Units	Notes
T_PHL	Output Propagation Delay High to	C _L = 15pF, R _L =	350Ω V _{CC} =3.3V	-	34	75		
I PHL	Low	C _L = 15pF, R _L =	C _L = 15pF, R _L = 350Ω V _{CC} =5.5V		34	75	ns	
T_PLH	Output Propagation Delay Low to	C _L = 15pF, R _L = 350Ω V _{CC} =3.3V		-	50	75	ns	
irun	High	C _L = 15pF, R _L =	350Ω V _{CC} =5.5V	-	39	75	110	
D	Pulse Width Distortion	C _L = 15pF, R _L =	350Ω Vcc=3.3V	-	16	34	20	
P _{WD}	Pulse Width Distortion	C _L = 15pF, R _L = 350Ω V _{CC} =5.5V		-	5	34	ns	
_	Output Dice Time	C _L = 15pF, R _L = 350Ω V _{CC} =3.3V C _L = 15pF, R _L = 350Ω V _{CC} =5.5V		-	37	-		
Tr	Output Rise Time			-	37	-	ns	
T _f	Output Fall Time	C_L = 15pF, R_L = 350 Ω V _{CC} =3.3V C_L = 15pF, R_L = 350 Ω V _{CC} =5.5V		-	10	1	20	
I f	Output Faii Time			-	10	ı	ns	
T _{ELH}	Enable Propagation Delay Low To High	VEH= 3.5V, C _L = 15pF, R _L =		-	15	-	ns	
T _{EHL}	Enable Propagation Delay High To Low	350Ω		-	15	-	ns	
	Common Mode Transient	I _F = 0mA, V _{CM} = 50Vp-p,	6N137	-	10000	-		
СМн	Immunity at Logic High	$V_{OH} = 30V_{P} - P$, $V_{OH} = 2.0V$, $R_{L} = 350\Omega$	CT2601	5000	10000	-	V/µs	



6N137, CT2601

10MBit/s High Speed Logic Gate Optocoupler

	I _F =7.5mA, Common Mode Transient V _{CM} = 50Vp-p,	I _F =7.5mA, V _{См} = 50Vp-p,	6N137	-	10000	-		
CM∟	Immunity at Logic Low	V _{OL} = 0.8V,	CT2601	5000	10000	-	V/µs	
		R _L = 350Ω	012001		. 5500			



Typical Characteristic Curves

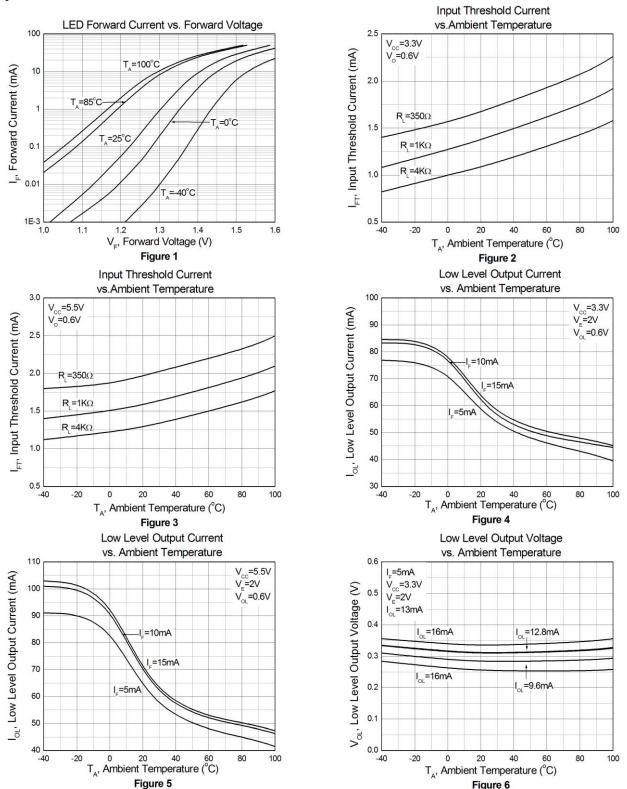
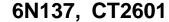
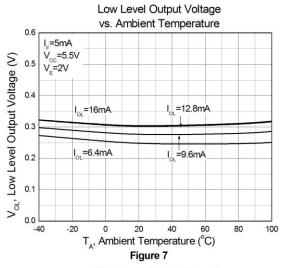


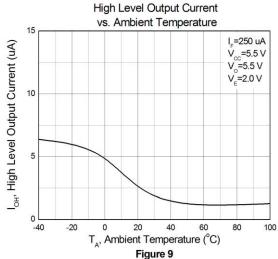
Figure 6

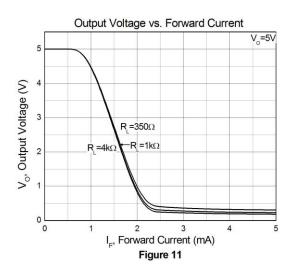


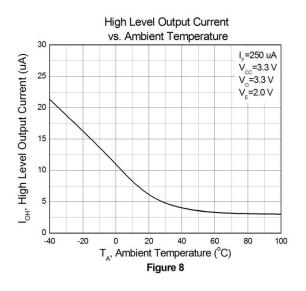


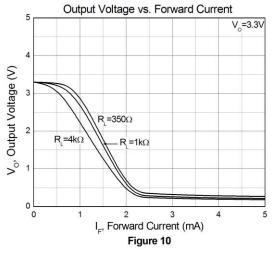
Typical Characteristic Curves

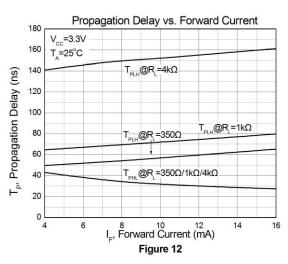


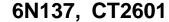




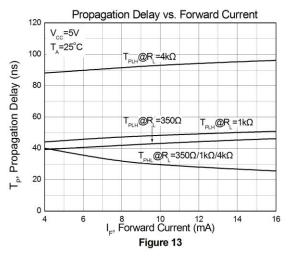


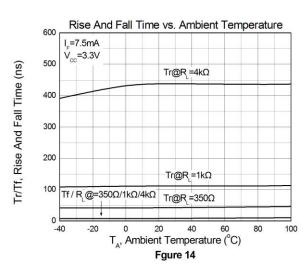


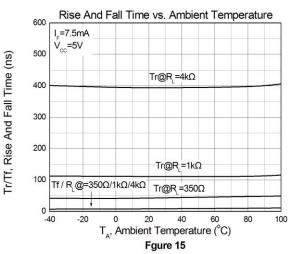


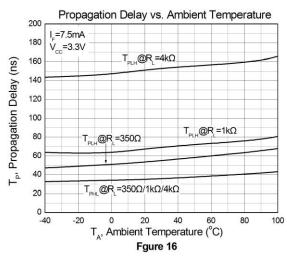


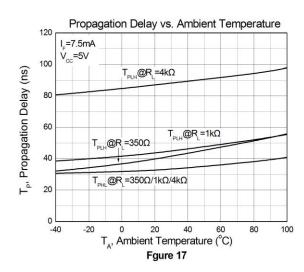


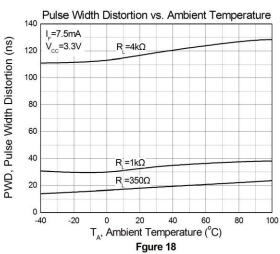


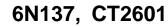




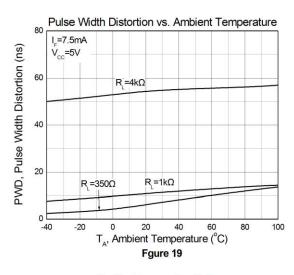


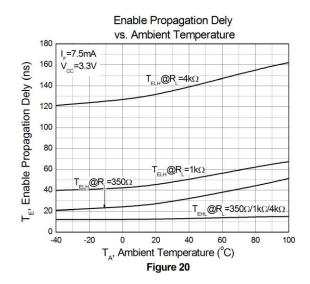


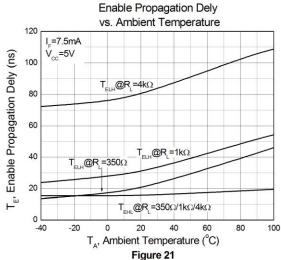






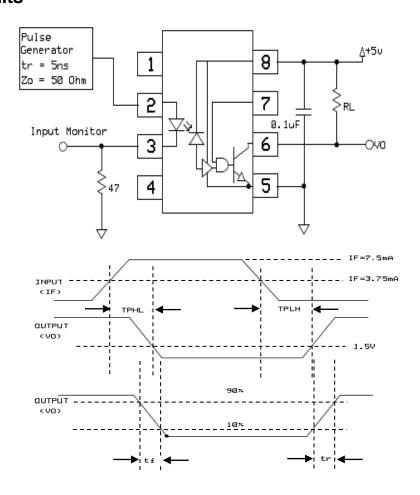








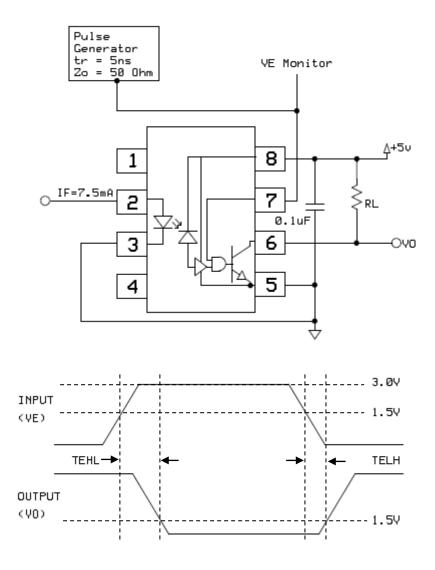
Test Circuits



Switching Time Test Circuit



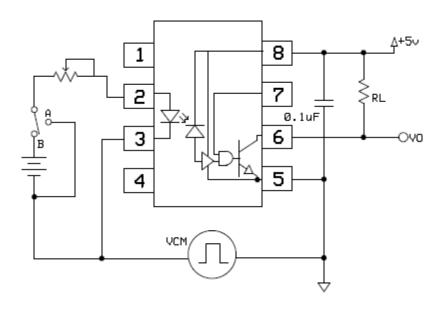
Test Circuits

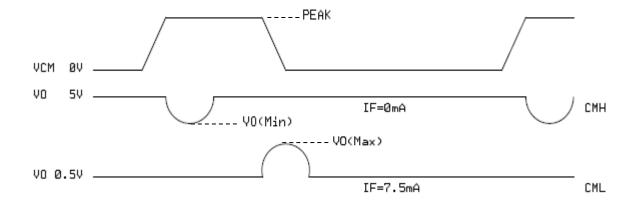


Enable Switching Time Test Circuit



Test Circuits



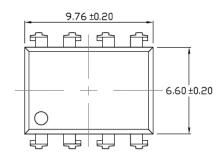


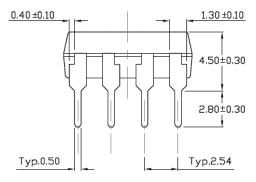
CMR Test Circuit

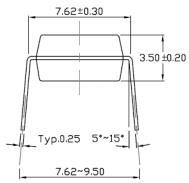


Package Dimension Dimensions in mm unless otherwise stated

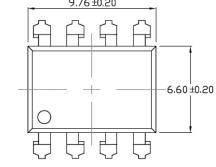
Standard DIP - Through Hole

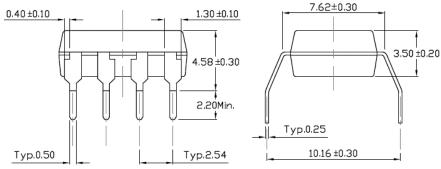






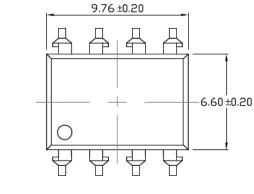
Gullwing (400mil) Lead Forming – Through Hole (M Type)

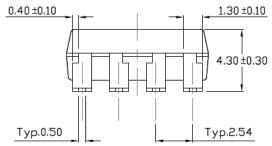


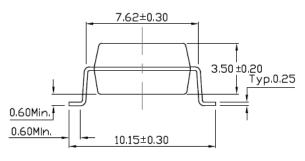




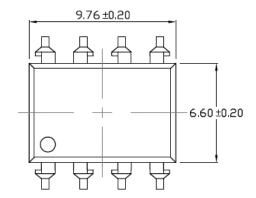
Surface Mount Lead Forming (S Type)

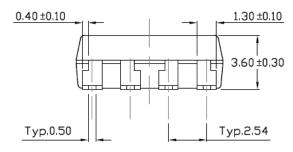


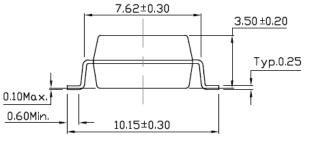




Surface Mount (Low Profile) Lead Forming (SL Type)

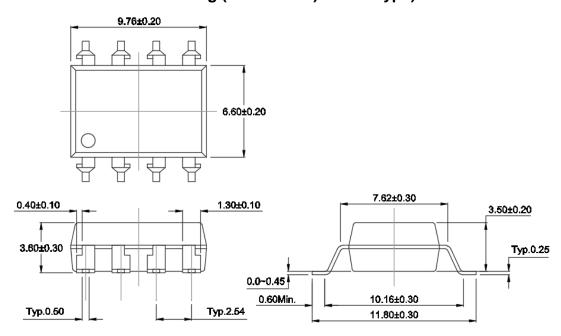




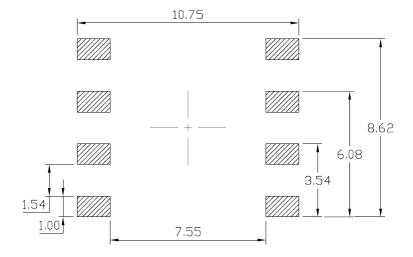




Wide Surface Mount Forming (Low Profile) - SLM Type)

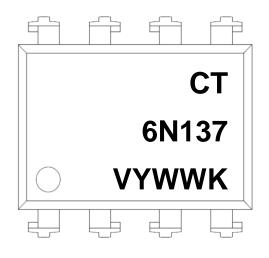


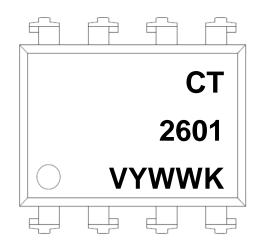
Recommended Solder Mask Dimensions in mm unless otherwise stated





Device Marking





Note:

CT: Denotes "CT Micro"
6N137: Product Number
2601: Product Number
V: VDE Option
Y: Fiscal Year
WW: Work Week

K : Production Code

Ordering Information

6N137(V)(Y)(Z)-G; CT2601(V)(Y)(Z)-G

CT = Denotes "CT Micro"

6N137 = Part Number 2601 = Part Number

V = VDE Option (V or None)

Y = Lead form option (S, SL, M, SLM or none)

Z = Tape and reel option (T1, T2 or none)

G = Material option (G: Green, None: Non-green)



6N137, CT2601

10MBit/s High Speed Logic Gate Optocoupler

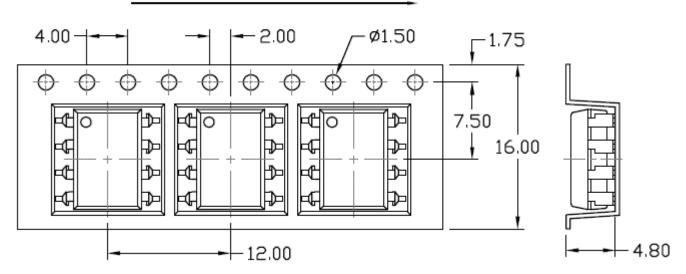
Option	Description	Quantity
None	Standard 8 Pin Dip	40 Units/Tube
М	Gullwing (400mil) Lead Forming	40 Units/Tube
S(T1)	Surface Mount Lead Forming – With Option 1 Taping	1000 Units/Reel
S(T2)	Surface Mount Lead Forming – With Option 2 Taping	1000 Units/Reel
SL(T1)	Surface Mount (Low Profile) Lead Forming– With Option 1 Taping	1000 Units/Reel
SL(T2)	Surface Mount (Low Profile) Lead Forming– With Option 2 Taping	1000 Units/Reel
SLM(T1)	Surface Mount (Gullwing) Lead Forming– With Option 1 Taping	1000 Units/Reel
SLM(T2)	Surface Mount (Gullwing) Lead Forming – With Option 2 Taping	1000 Units/Reel



Carrier Tape Specifications Dimensions in mm unless otherwise stated

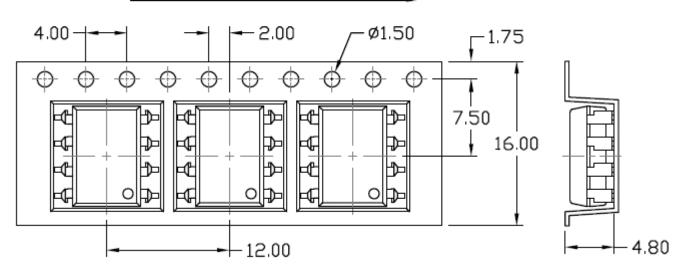
Option S(T1) & SL(T1)

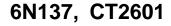
Input Direction



Option S(T2) & SL(T2)

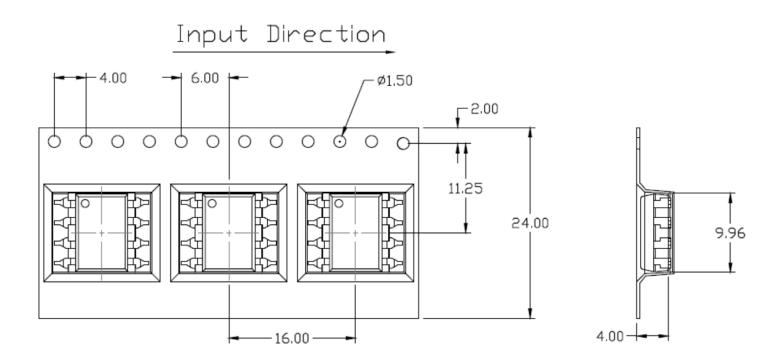
Input Direction



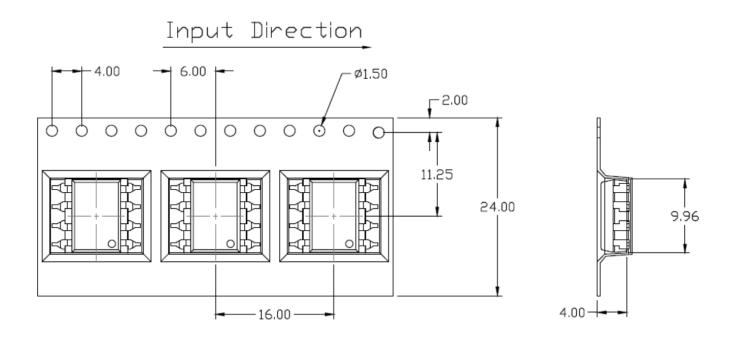




Option SLM(T1)



Option SLM(T2)





Wave soldering (follow the JEDEC standard JESD22-A111)

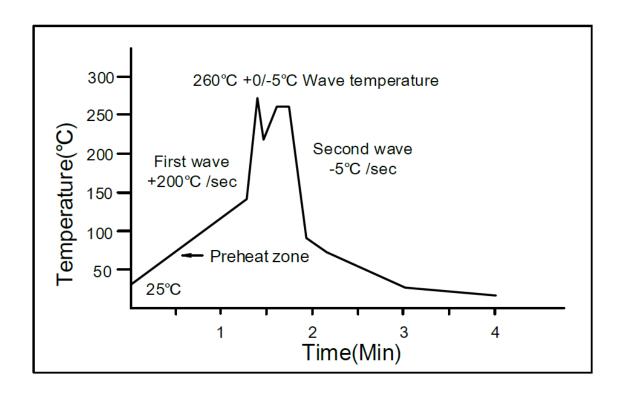
One time soldering is recommended within the condition of temperature.

Temperature: 260+0/-5°C.

Time: 10 sec.

Preheat temperature:25 to 140°C.

Preheat time: 30 to 80 sec.



Iron soldering (follow the standard MIL-STD 202G, Method 210F)

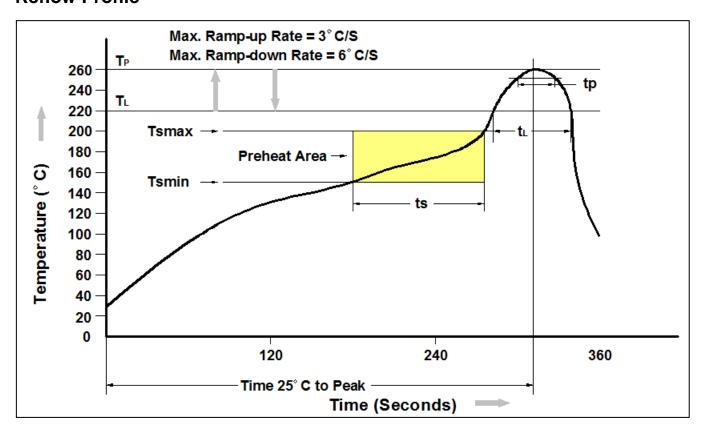
Allow single lead soldering in every single process.

One time soldering is recommended. Temperature: 350+±10°C

Time: 5 sec max.



Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t∟ to t _P)	3°C/second max.
Liquidous Temperature (T _L)	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t _P) within 5°C of 260°C	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.





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- A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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